

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	I_D
-20V	3mΩ@-4.5V	-70A
	4mΩ@-2.5V	
	8mΩ@-1.8V	

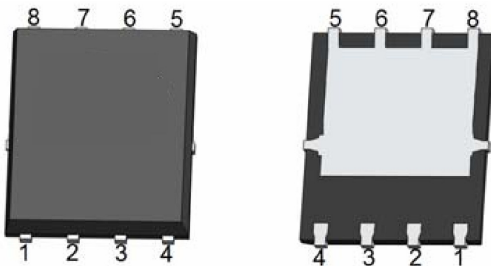
Feature

- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high EAS

Application

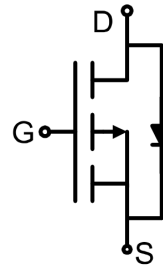
- Battery and loading switching

Package

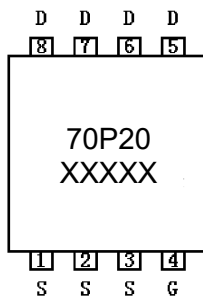


DFN5X6-8L

Circuit diagram



Marking



Absolute maximum ratings (Ta=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _{GS}	±10	V
Continuous Drain Current	I _D	-70	A
Pulsed Drain Current	I _{DM}	-280	A
Power Dissipation	P _D	130	W
Thermal Resistance, Junction-to-Case	R _{θJC}	1.6	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55 ~ +150	°C

Electrical characteristics (T_A=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-20			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = -20V, V _{GS} = 0V			-1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±10V, V _{DS} = 0V			±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-0.4		-1.0	V
Drain-source on-resistance ¹⁾	R _{DS(on)}	V _{GS} = -4.5V, I _D = -20A		2.3	3	mΩ
		V _{GS} = -2.5V, I _D = -20A		2.8	4	
		V _{GS} = -1.8V, I _D = -20A		3.8	8	
Forward transconductance ¹⁾	g _{FS}	V _{DS} = -5V, I _D = -20A	100			S
Dynamic characteristics²⁾						
Input Capacitance	C _{iss}	V _{DS} = -10V, V _{GS} = 0V, f = 1MHz		4950		pF
Output Capacitance	C _{oss}			380		
Reverse Transfer Capacitance	C _{rss}			290		
Total Gate Charge	Q _g	V _{DS} = -10V, V _{GS} = -4.5V, I _D = -20A		100		nC
Gate-Source Charge	Q _{gs}			21		
Gate-Drain Charge	Q _{gd}			32		
Turn-on delay time	t _{d(on)}	V _{DD} = -10V, V _{GS} = -4.5V, R _L = 0.5Ω, R _{GEN} = 3Ω		20		nS
Turn-on rise time	t _r			50		
Turn-off delay time	t _{d(off)}			100		
Turn-off fall time	t _f			40		
Source-Drain Diode characteristics						
Diode Forward Current ¹⁾	I _S				-70	A
Diode Forward voltage	V _{DS}	V _{GS} = 0V, I _S = -20A			-1.2	V
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = -10A		48		nS
Reverse Recovery Charge	Q _{rr}	di/dt = 100A/μs ¹⁾		55		nC

Notes:

- 1) Pulse Test: Pulse Width < 300μs, Duty Cycle ≤ 2%.
- 2) Guaranteed by design, not subject to production testing.

Typical Characteristics

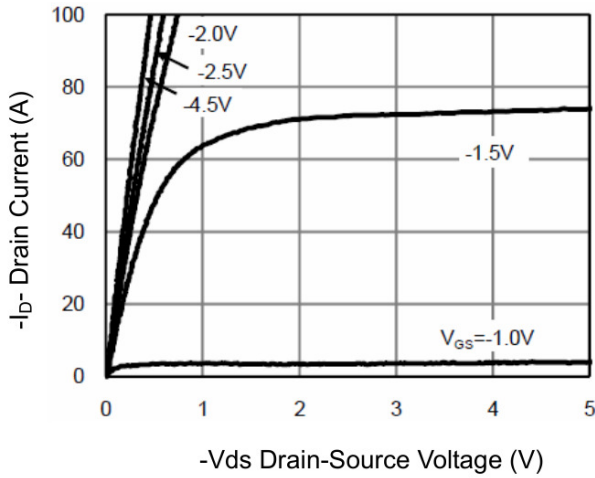


Figure 1 Output Characteristics

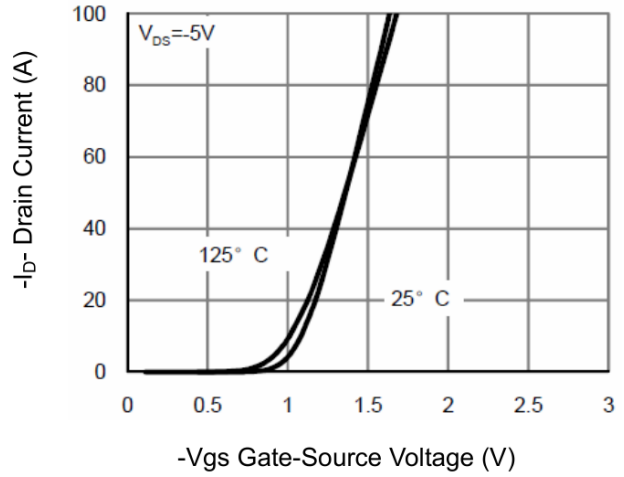


Figure 2 Transfer Characteristics

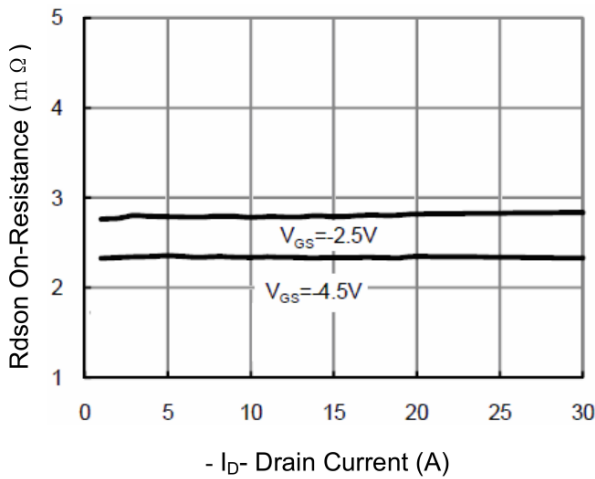


Figure 3 Rdson- Drain Current

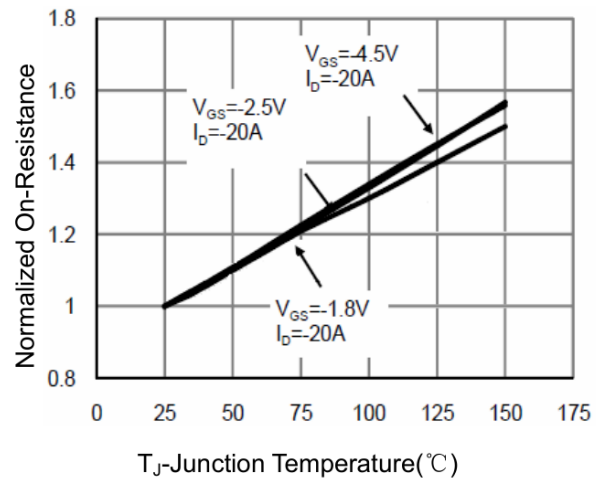


Figure 4 Rdson-Junction Temperature

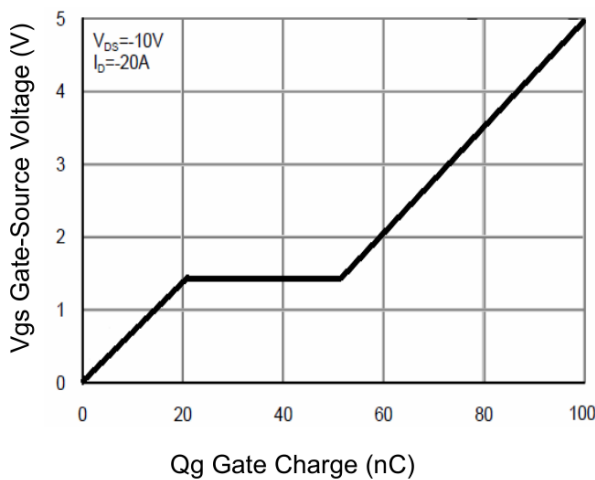


Figure 5 Gate Charge

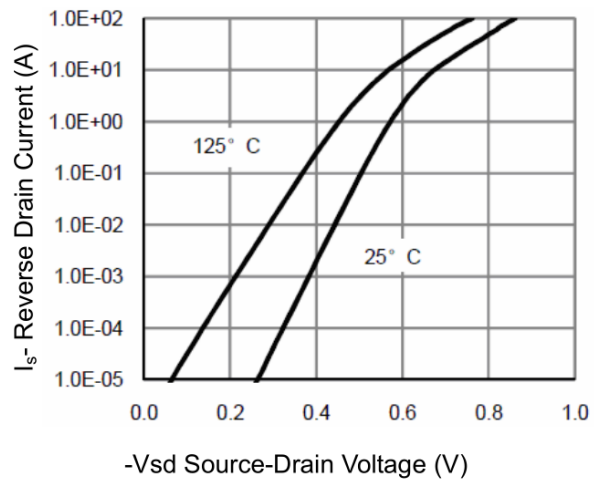
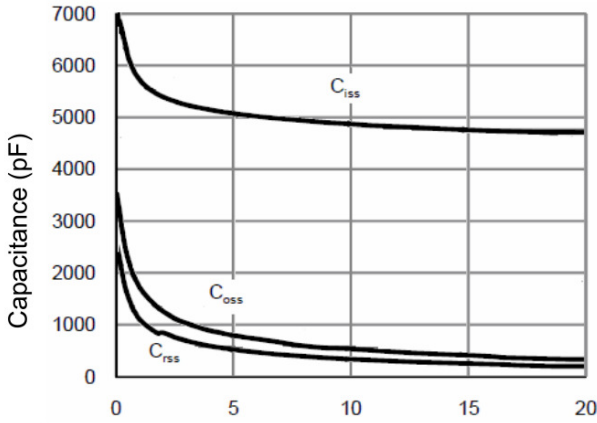
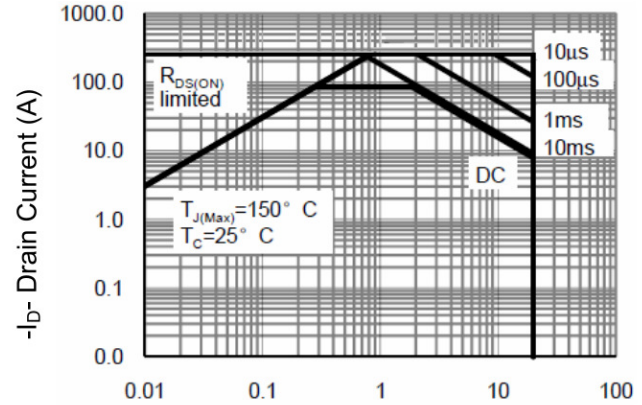


Figure 6 Source- Drain Diode Forward

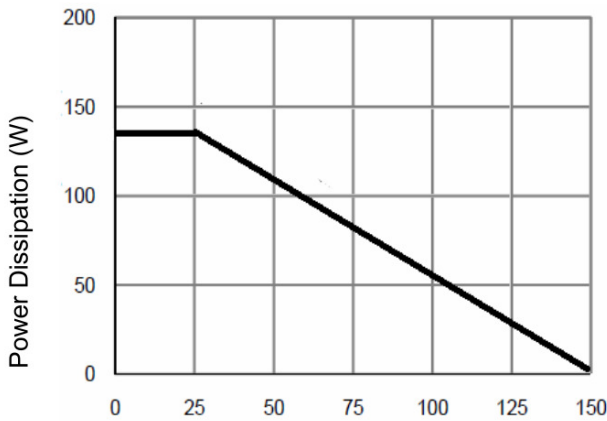
Typical Characteristics



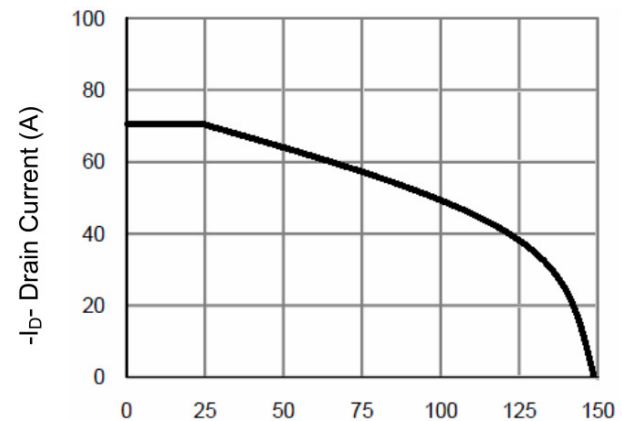
-Vds Drain-Source Voltage (V)
Figure 7 Capacitance vs Vds



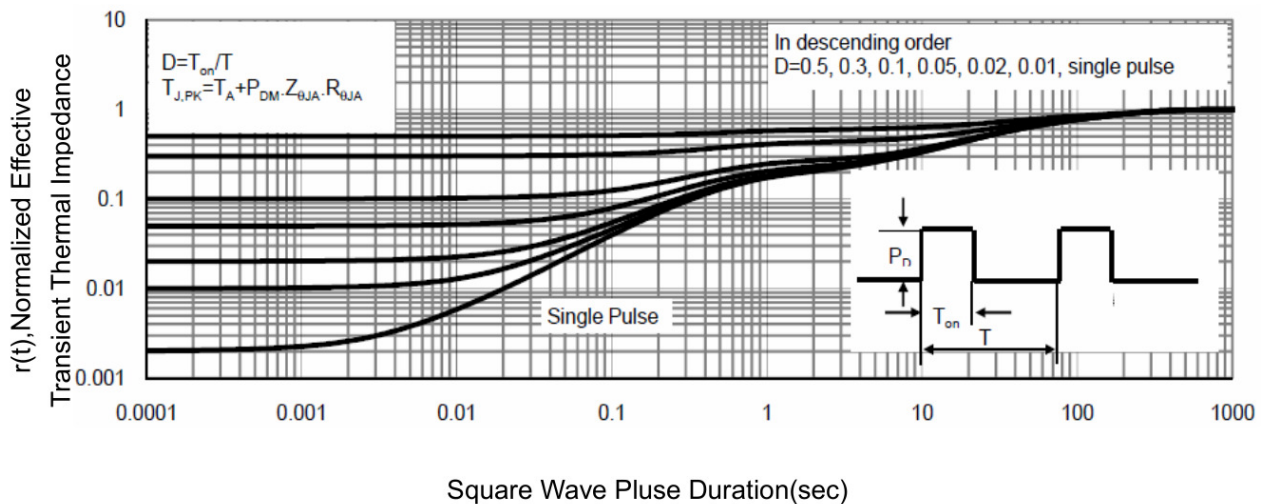
-Vds Drain-Source Voltage (V)
Figure 8 Safe Operation Area



T_J-Junction Temperature(°C)
Figure 9 Power De-rating

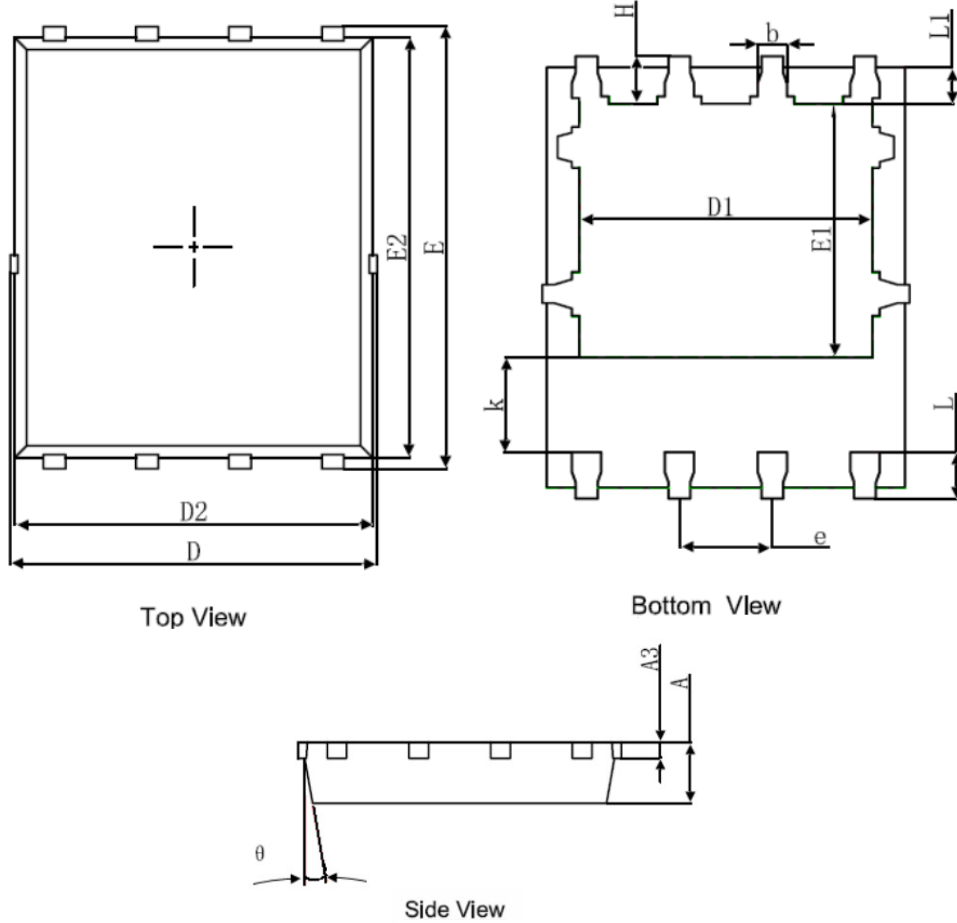


T_J-Junction Temperature(°C)
Figure 10 -Current De-rating



Square Wave Pulse Duration(sec)
Figure 11 Normalized Maximum Transient Thermal Impedance

DFN5X6-8L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254REF.		0.010REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	3.910	4.110	0.154	0.162
E1	3.375	3.575	0.133	0.141
D2	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	8°	12°	8°	12°